



3

DECLARATION FOR PATENT APPLICATION

As below named inventors, we hereby declare that:

Our residence, post office address and citizenship are as stated below next to our name.

We believe we are an original, first and joint inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled:

STRUCTURE AND METHOD FOR DEPOSITING SOLDER BUMPS ON A WAFER

the specification of which (check one)

- ☐ is attached hereto.
☒ was filed by an authorized person on my behalf on
April 12, 2001 as Application Serial No. 09/834,273
and was amended on n/a
(if applicable)

We hereby state that we have reviewed and understand the contents of the above-identified specification, including the claims as amended by any amendment referred to above.

We acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, §1.56(a).

We hereby claim foreign priority benefits under Title 35, United States Code, §119 of any foreign application(s) for patent or inventor's certificate listed below and so identified, and we have also identified below any foreign application for patent or inventor's certificate on this invention filed by us or our legal representatives or assigns and having a filing date before that of the application on which priority is claimed.

Number
NONE

Country

Day/Month/Year Filed

Priority
Claimed
(Yes or No)

We hereby claim the benefit under Title 35, United States Code, §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, we acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, §1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

Application Serial No.
NONE

Filing Date

Status

We hereby declare that all statements made herein of our own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under §1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

We hereby appoint the following attorneys and patent agent, with full power of substitution and revocation, to prosecute this application and to transact all business in the United States Patent and Trademark Office connected therewith and request that all correspondence and telephone calls in respect to this application be directed to COUDERT BROTHERS, 600 Beach Street, 3rd Floor, San Francisco, CA 94109, Telephone No. (415) 409-2900:

<u>Attorney</u>	<u>Reg. No.</u>
J. Bruce McCubbrey	20,687
Donald L. Bartels	28,282
David Schnapf	31,566
Robert D. Becker	37,778
Richard A. Dannells, Jr.	22,654
James W. Drapinski	46,242
John W. Carpenter	26,447

<u>Patent Agents</u>	
Hal R. Yeager	35,419
Steven R. Vosen	45,186

Full name of first joint inventor:

Hunt Hang Jiang

Inventor's signature:

Hunt Hang Jiang

Date:

July 10, 2001

Residence and Post Office
Address:

1045 Regency Knoll Dr.
San Jose, CA 95129

Citizenship:

United States

Full name of second joint inventor:

Mark McCormack

Inventor's signature: _____

Date: _____

Residence and Post Office
Address:

2356 White Oak Place
Livermore, CA 94550

Citizenship:

United States of America

Full name of third joint inventor:

Lei Zhang

Inventor's signature: _____

Date: _____

Residence and Post Office
Address:

4078 Lakeside Drive
San Jose, CA 95148

Citizenship: _____

Address for Correspondence:

COUDERT BROTHERS
600 Beach Street, 3rd Floor
San Francisco, CA 94109



3

DECLARATION FOR PATENT APPLICATION

As below named inventors, we hereby declare that:

Our residence, post office address and citizenship are as stated below next to our name.

We believe we are an original, first and joint inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled:

STRUCTURE AND METHOD FOR DEPOSITING SOLDER BUMPS ON A WAFER

the specification of which (check one)

- ☐ is attached hereto.
☒ was filed by an authorized person on my behalf on
April 12, 2001 as Application Serial No. 09/834,273
and was amended on n/a
(if applicable)

We hereby state that we have reviewed and understand the contents of the above-identified specification, including the claims as amended by any amendment referred to above.

We acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, §1.56(a).

We hereby claim foreign priority benefits under Title 35, United States Code, §119 of any foreign application(s) for patent or inventor's certificate listed below and so identified, and we have also identified below any foreign application for patent or inventor's certificate on this invention filed by us or our legal representatives or assigns and having a filing date before that of the application on which priority is claimed.

<u>Number</u>	<u>Country</u>	<u>Day/Month/Year Filed</u>	<u>Priority Claimed (Yes or No)</u>
NONE			

We hereby claim the benefit under Title 35, United States Code, §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, we acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, §1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

Application Serial No.
NONE

Filing Date

Status

We hereby declare that all statements made herein of our own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under §1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

We hereby appoint the following attorneys and patent agent, with full power of substitution and revocation, to prosecute this application and to transact all business in the United States Patent and Trademark Office connected therewith and request that all correspondence and telephone calls in respect to this application be directed to COUDERT BROTHERS, 600 Beach Street, 3rd Floor, San Francisco, CA 94109, Telephone No. (415) 409-2900:

<u>Attorney</u>	<u>Reg. No.</u>
J. Bruce McCubbrey	20,687
Donald L. Bartels	28,282
David Schnapf	31,566
Robert D. Becker	37,778
Richard A. Dannells, Jr.	22,654
James W. Drapinski	46,242
John W. Carpenter	26,447

<u>Patent Agents</u>	
Hal R. Yeager	35,419
Steven R. Vosen	45,186

Full name of first joint inventor: Hunt Hang Jiang

Inventor's signature: _____

Date: _____

Residence and Post Office Address: 1045 Regency Knoll Dr.
San Jose, CA 95129

Citizenship: _____

Full name of second joint inventor:

Mark McCormack

Inventor's signature:

Mark McCormack

Date:

7/06/01

Residence and Post Office
Address:

2356 White Oak Place
Livermore, CA 94550

Citizenship:

United States of America

Full name of third joint inventor:

Lei Zhang

Inventor's signature:

Date:

Residence and Post Office
Address:

4078 Lakeside Drive
San Jose, CA 95148

Citizenship:

Address for Correspondence:

COUDERT BROTHERS
600 Beach Street, 3rd Floor
San Francisco, CA 94109



3

DECLARATION FOR PATENT APPLICATION

As below named inventors, we hereby declare that:

Our residence, post office address and citizenship are as stated below next to our name.

We believe we are an original, first and joint inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled:

STRUCTURE AND METHOD FOR DEPOSITING SOLDER BUMPS ON A WAFER

the specification of which (check one)

- ☐ is attached hereto.
☒ was filed by an authorized person on my behalf on
April 12, 2001 as Application Serial No. 09/834,273
and was amended on n/a
(if applicable)

We hereby state that we have reviewed and understand the contents of the above-identified specification, including the claims as amended by any amendment referred to above.

We acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, §1.56(a).

We hereby claim foreign priority benefits under Title 35, United States Code, §119 of any foreign application(s) for patent or inventor's certificate listed below and so identified, and we have also identified below any foreign application for patent or inventor's certificate on this invention filed by us or our legal representatives or assigns and having a filing date before that of the application on which priority is claimed.

Number
NONE

Country

Day/Month/Year Filed

Priority
Claimed
(Yes or No)

We hereby claim the benefit under Title 35, United States Code, §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, we acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, §1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

Application Serial No.
NONE

Filing Date

Status

We hereby declare that all statements made herein of our own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under §1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

We hereby appoint the following attorneys and patent agent, with full power of substitution and revocation, to prosecute this application and to transact all business in the United States Patent and Trademark Office connected therewith and request that all correspondence and telephone calls in respect to this application be directed to COUDERT BROTHERS, 600 Beach Street, 3rd Floor, San Francisco, CA 94109, Telephone No. (415) 409-2900:

<u>Attorney</u>	<u>Reg. No.</u>
J. Bruce McCubbrey	20,687
Donald L. Bartels	28,282
David Schnapf	31,566
Robert D. Becker	37,778
Richard A. Dannells, Jr.	22,654
James W. Drapinski	46,242
John W. Carpenter	26,447

<u>Patent Agents</u>	
Hal R. Yeager	35,419
Steven R. Vosen	45,186

Full name of first joint inventor:

Hunt Hang Jiang

Inventor's signature:

Date:

Residence and Post Office
Address:

1045 Regency Knoll Dr.
San Jose, CA 95129

Citizenship:

Full name of second joint inventor:

Mark McCormack

Inventor's signature:

Date:

Residence and Post Office
Address:

2356 White Oak Place
Livermore, CA 94550

Citizenship:

United States of America

Full name of third joint inventor:

Lei Zhang

Inventor's signature:

Date:

Residence and Post Office
Address:

4078 Lakeside Drive
San Jose, CA 95148

Citizenship:

P. R. China

Address for Correspondence:

COUDERT BROTHERS
600 Beach Street, 3rd Floor
San Francisco, CA 94109